

# Product/Process Change Notification

N° 2021-172-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

## Several changes affecting product TLE8444SL

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2023-03-19.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46”, which stipulates: “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”  
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG

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[Management Board](#) Jochen Hanebeck (CEO), Constanze Hufenbecher, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg

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## Products affected

Please refer to attached affected product list PCN\_2021-172-A\_[customer-no].pdf

## Detailed change information

**Subject:** Several changes affecting product TLE8444SL

**Reason/Motivation:** Copper wire bonding is part of Infineon's continuous drive to deliver high performance products. A copper wire enables superior electrical, thermal and reliability performance making it an excellent interconnect solution for automotive packaging.

| Description   | Old                  | New              |
|---|----------------------|------------------|
| <b>DATA SHEET: Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification</b> | Rev. 1.10            | Rev. 1.20        |
| <b>DESIGN: Design changes in routing .</b>  | current chip routing | new chip routing |
| <b>PROCESS - ASSEMBLY: Die attach material</b>  | glue: EN4900GC       | glue: AB3230     |
| <b>PROCESS - ASSEMBLY: Change of wire bonding</b>   | Au wire, 30µm        | Cu wire, 30µm    |

## Product identification

Traceability assured via date code.  
No change in SP ordering number.

## Anticipated impact of change

Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in fit, form and function expected.

DeQuMa-ID(s): SEM-DS-01 / SEM-DE-02 / SEM-PA-07 / SEM-PA-08

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## Attachments

PCN\_2021-172-A\_[customer-no].pdf affected product list

## Time schedule

|                                |            |
|--------------------------------|------------|
| Final qualification report     | available  |
| First samples available        | on request |
| Intended start of delivery [1] | 2023-08-31 |
| Last order date (LOD) [2]      | 2023-08-31 |
| Last delivery date (LDD) [3]   | 2024-02-28 |

If you have any questions, please do not hesitate to contact your local sales office.

## PCN 2021-172-A



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Affected products sold to DIGI-KEY (4002348)

| Sales name | SP number   | OPN            | Package      | Customer part number |
|------------|-------------|----------------|--------------|----------------------|
| TLE8444SL  | SP000394373 | TLE8444SLXUMA1 | PG-SSOP-24-7 | TLE8444SLXUMA1       |